

# Single-photon Cameras for Quantum Imaging Applications

Edoardo Charbon

November 22<sup>nd</sup>, 2023

# Acknowledgements

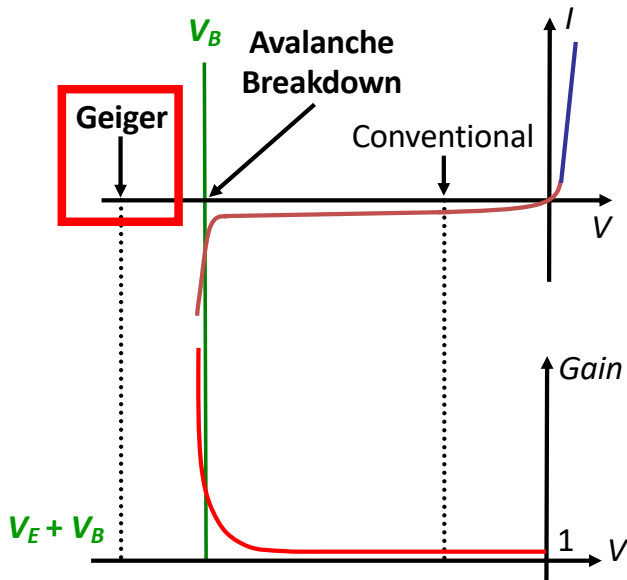
Swiss National Science Foundation  
European Commission, STW/NOW

Global Foundries, Canon, and many  
others.



# **Solid-state photon counting:** APDs and GM-APDs/SPADs

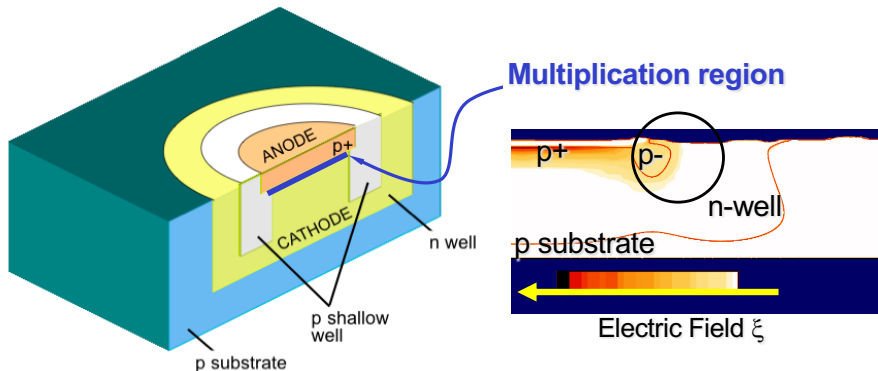
# SPAD or Geiger-Mode APD





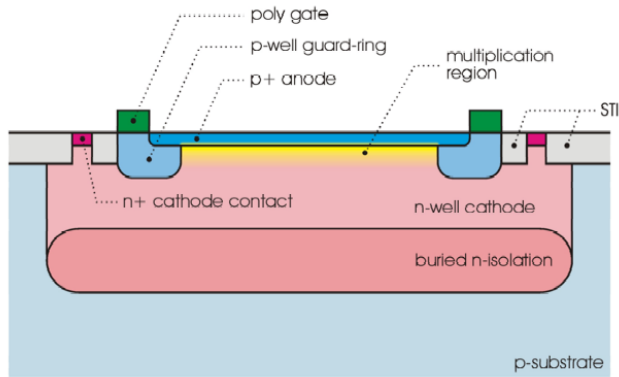
# The first CMOS SPAD

- Implemented entirely using standard layers and conventional process steps!
- Further miniaturization, thinner devices, lower voltages



Rochas *et al.*

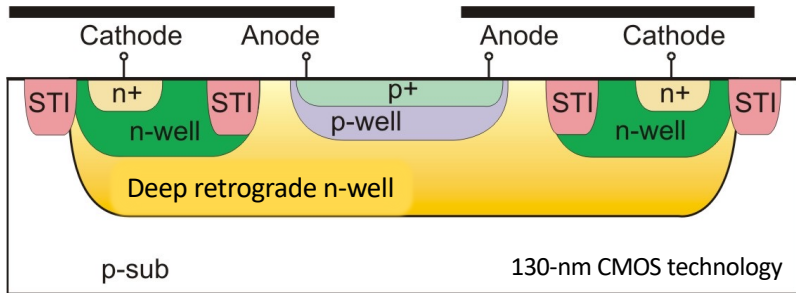
# The first deep-submicron CMOS SPAD



Niclass et al. 2007

- First deep-submicron CMOS structure (130nm)
- In DSM processes, high doping and shallow implants, thus high DCR
- Quasi neutral field region at the edges, thus long diffusion tail in the time response

# The first industrial SPAD



Niclass et al. 2007 – Richardson et al. – Pellegrini et al.

- Guard ring implicitly obtained from retrograde well
- Suitable for deep-submicron processes (in this case 130nm)
- Compatible with triple-well process
- Good DCR performance

# SPAD with fully-depleted avalanche region

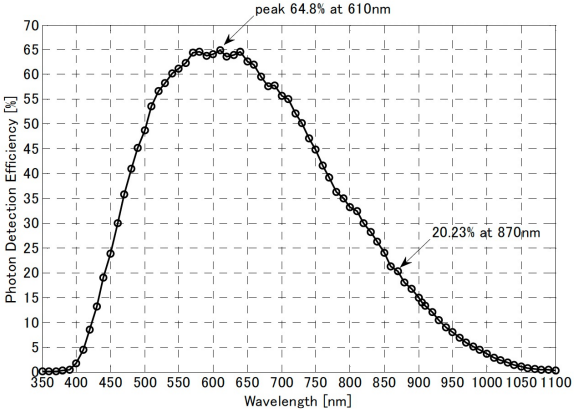
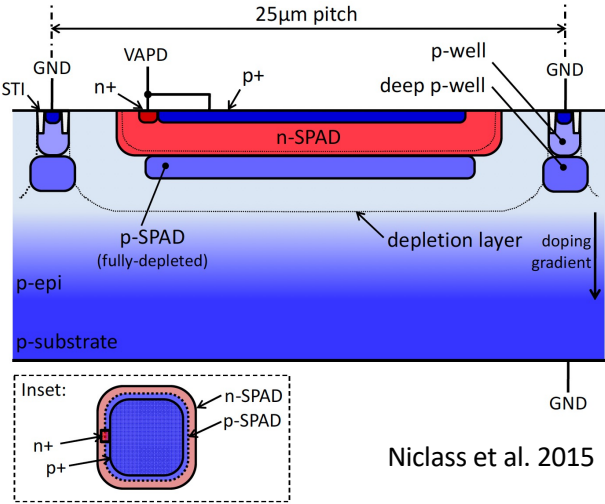


Fig. 10. Photon detection efficiency as a function of signal wavelength at an excess bias of 5V.

# Recent advances

# The phenomenal SPAD CIS evolution

- Timing resolution (**100ps** → **7.5ps**)
- Sensitivity
  - Photon Detection Probability (PDP) (**10%** → **90%**)
  - Fill-factor (**1%** → **80%**)
- Dead time (**100ns** → **1.5ns**)
- Dark counts (**kcps** → **cps** → **mcps**)
- Afterpulsing (**10%** → **0.1%**)

cps = counts per second

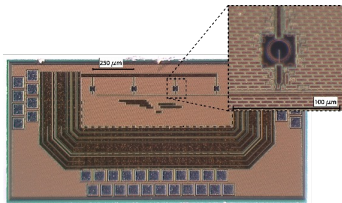
kcps =  $10^3$  cps

mcps =  $10^{-3}$  cps

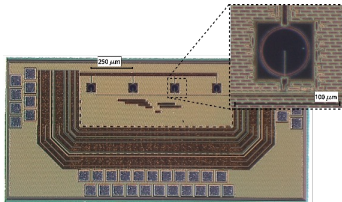


# The power of integration

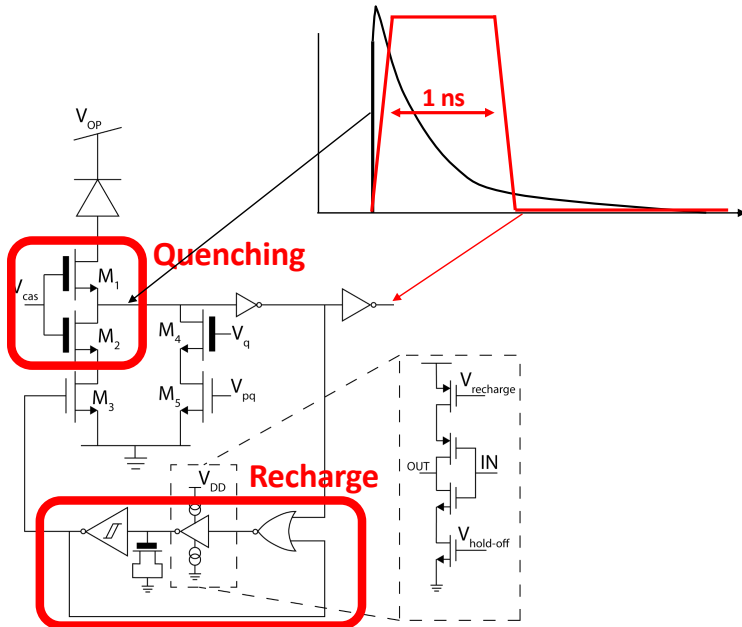
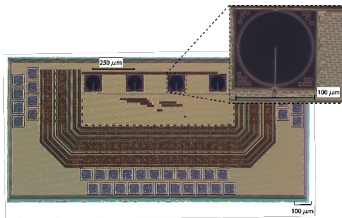
25 $\mu\text{m}$



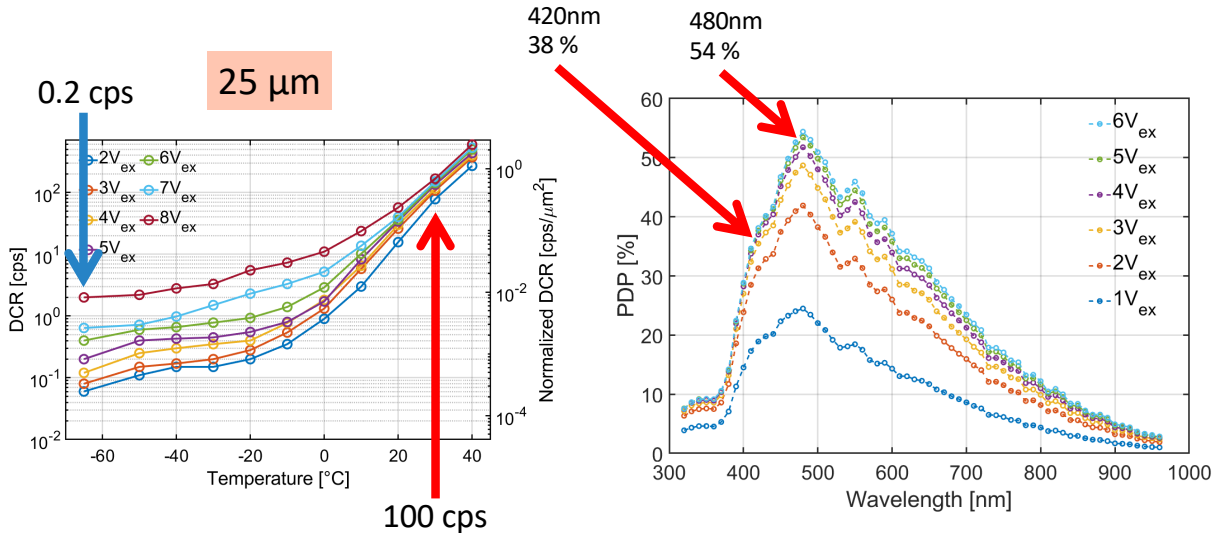
50 $\mu\text{m}$



100 $\mu\text{m}$

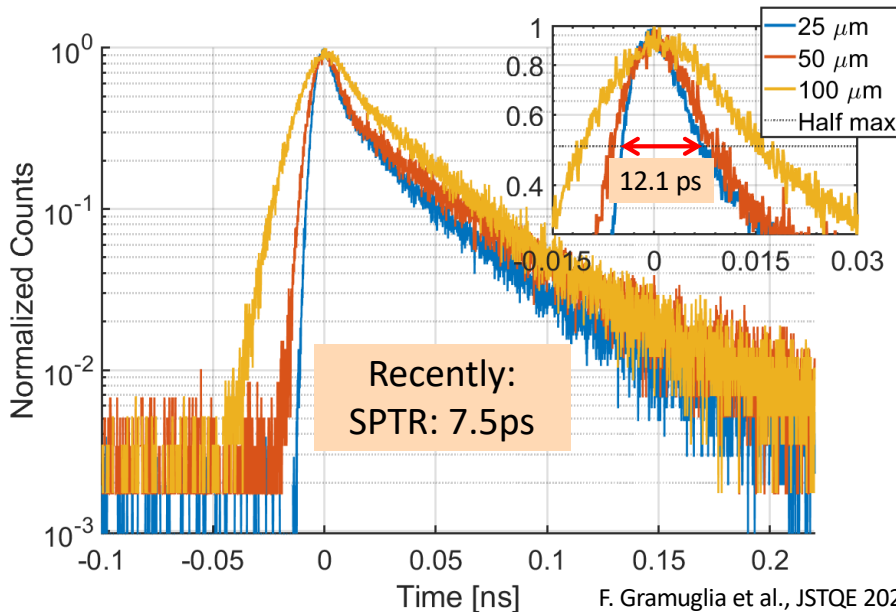


# Sensitivity (PDP) and noise (DCR)



F. Gramuglia et al., JSTQE 2021

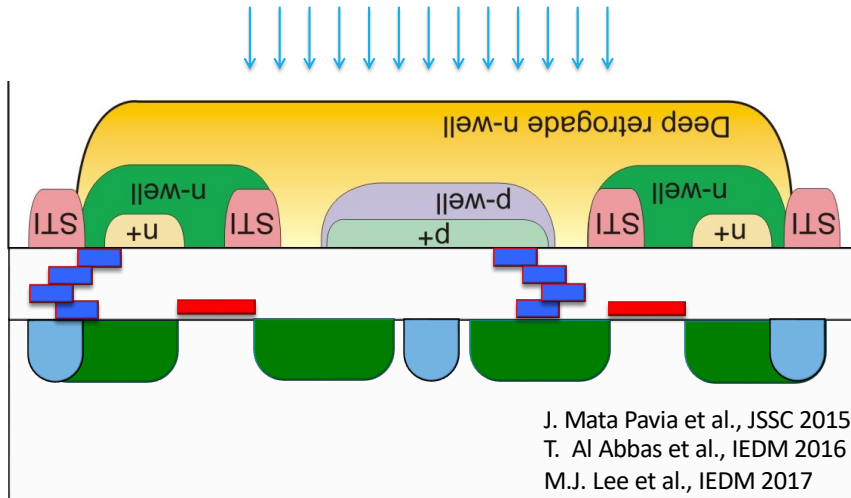
# Timing resolution (SPTR)



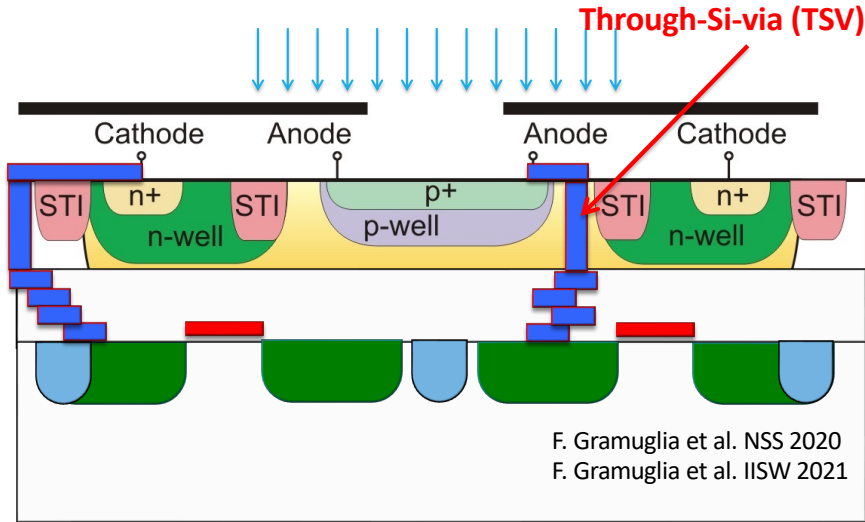
F. Gramuglia et al., JSTQE 2021

F. Gramuglia et al., Frontiers in Physics, 2022

# 3D stacking (backside illumination – BSI)

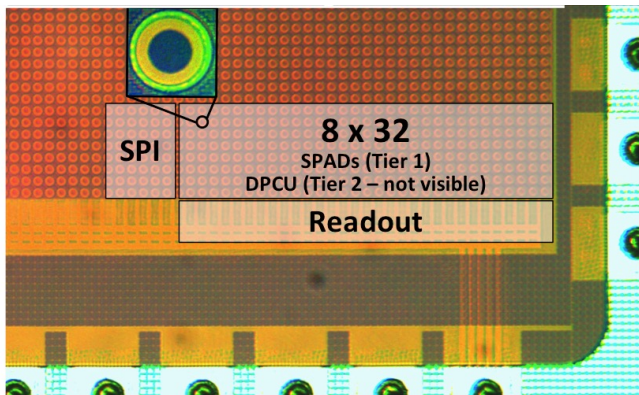


# 3D stacking (frontside illumination – FSI)



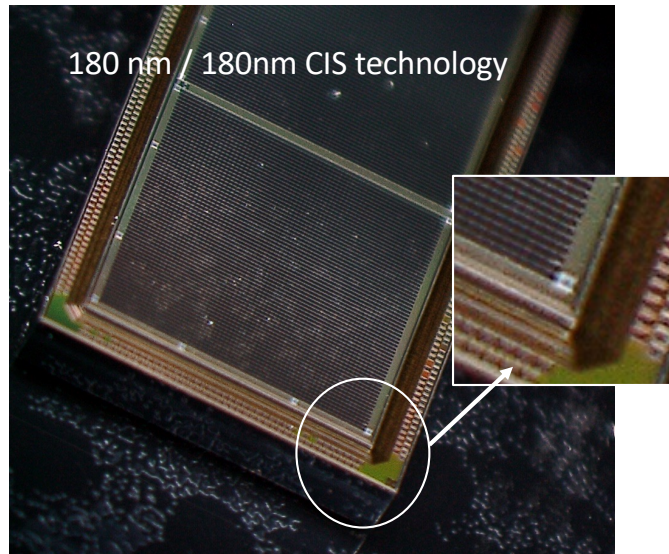
# 3D-stacked BSI & FSI chips

45 nm / 65nm & 22nm TSMC technology



A. Ximenes et al. ISSCC 2018 / JSSC 2019  
P. Padmanabhan et al. ISSCC 2021

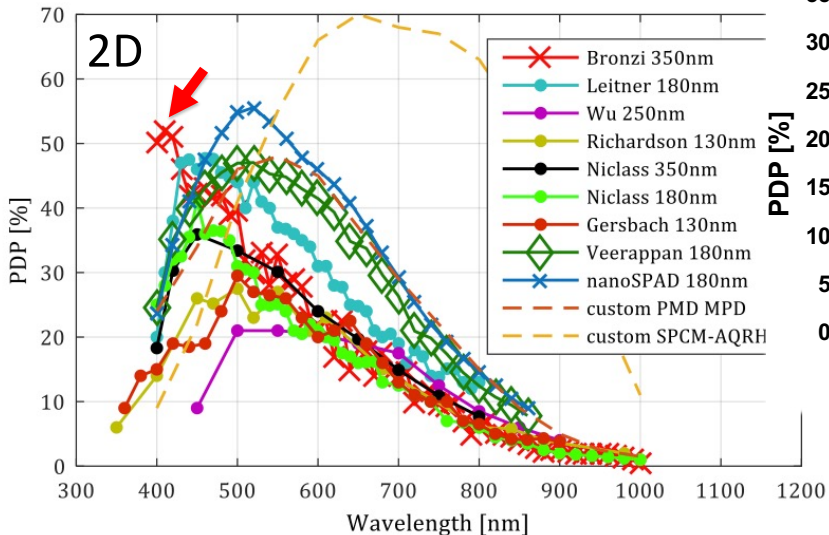
180 nm / 180nm CIS technology



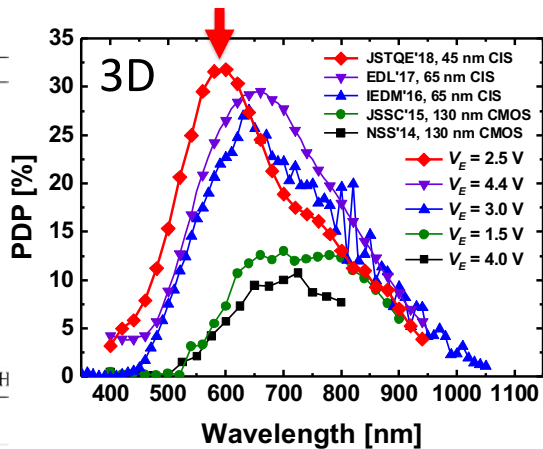
F. Gramuglia et al. NSS 2020 / IISW 2021



# FSI vs. BSI



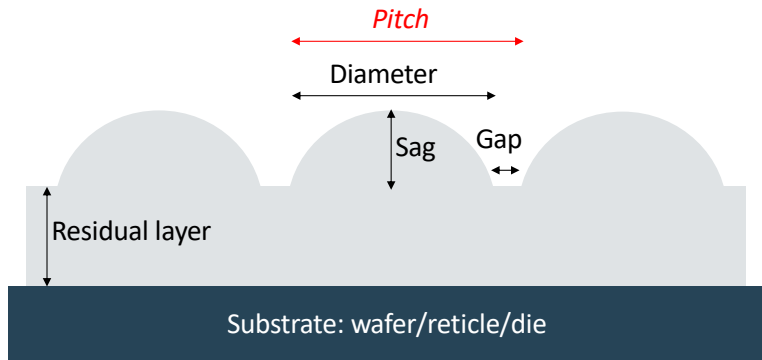
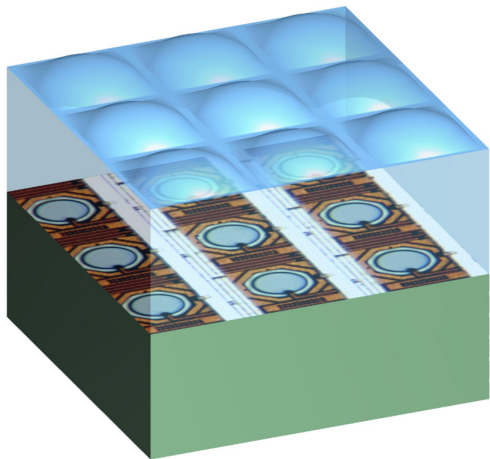
C. Veerappan & E. Charbon, TED 2016



M.-J. Lee *et al.*, Jpn. J. Appl. Phys'18

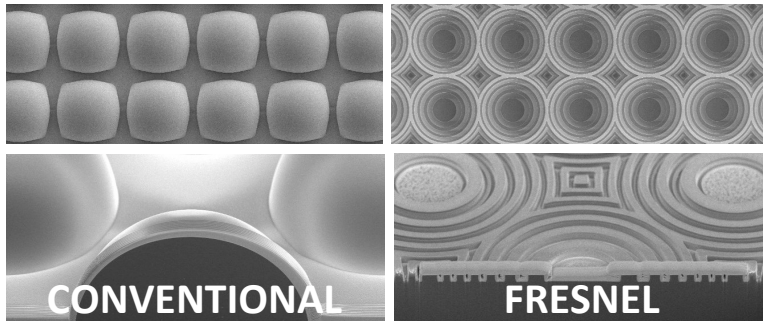
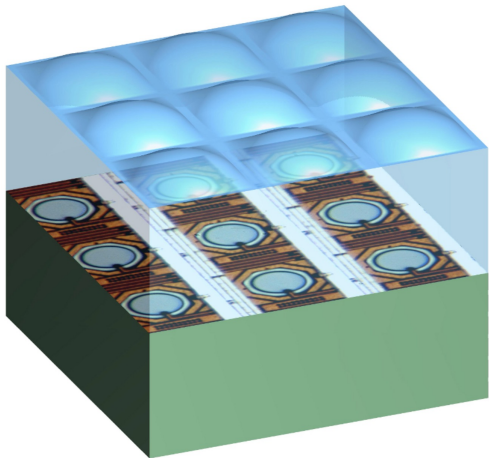
# Optical interfaces

# Optical microlenses



Mata Pavia et al. 2014 – Ximenes et al. 2018 – Bruschini et al. 2023

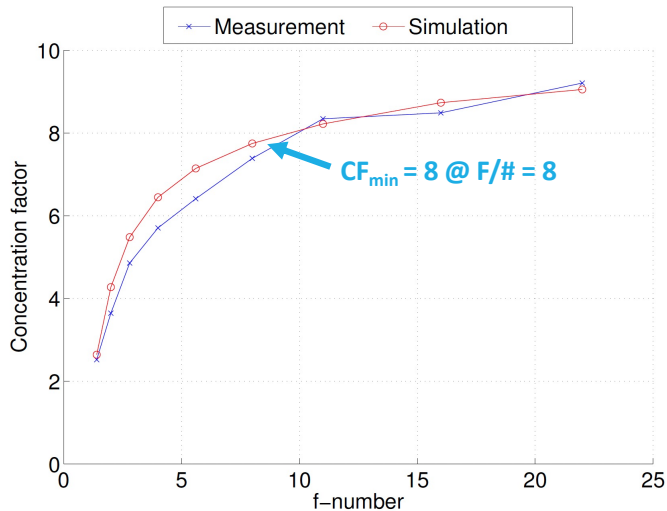
# Optical microlenses



Ximenes et al. 2018

Mata Pavia et al. 2014 – Ximenes et al. 2018 – Bruschini et al. 2023

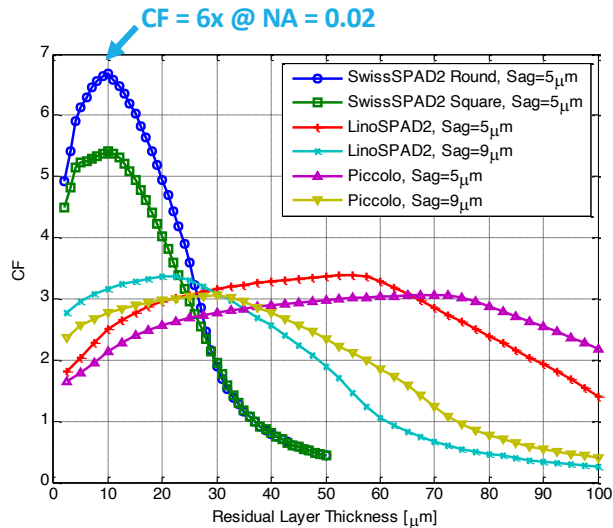
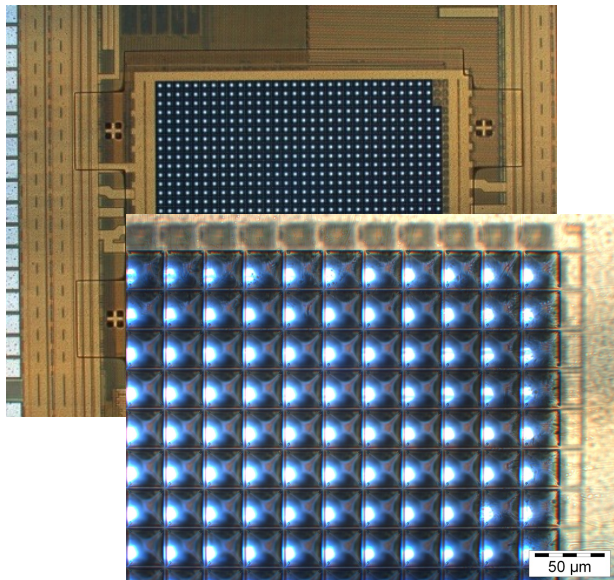
# Concentration factor



Mata Pavia et al. 2014

CF = concentration factor

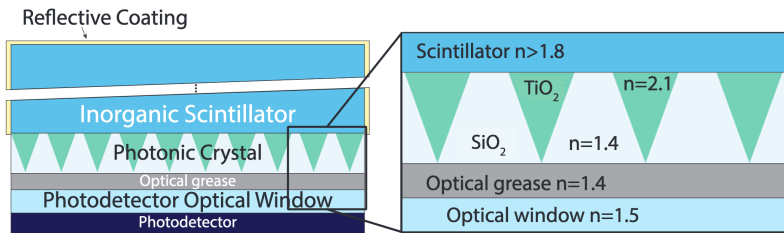
# CF for different SPADs



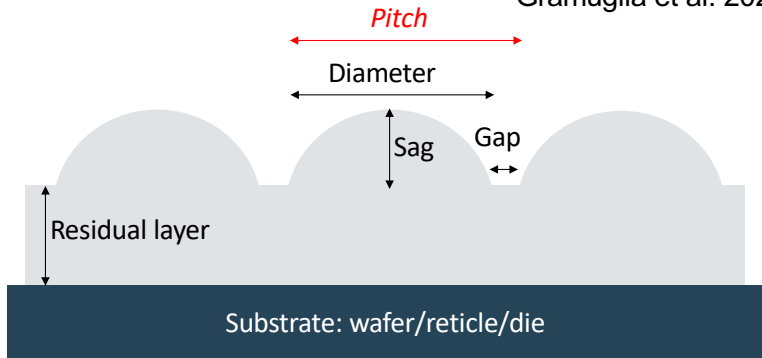
Bruschini et al. 2023



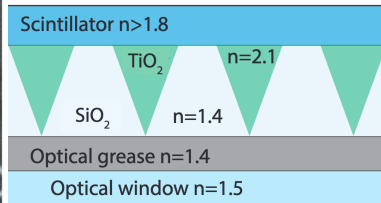
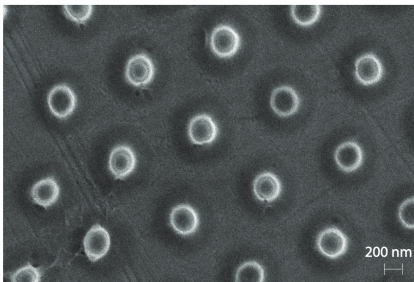
# Optimizing microlens-scintillator interfaces



Gramuglia et al. 2021



# Optimizing microlens-scintillator interfaces



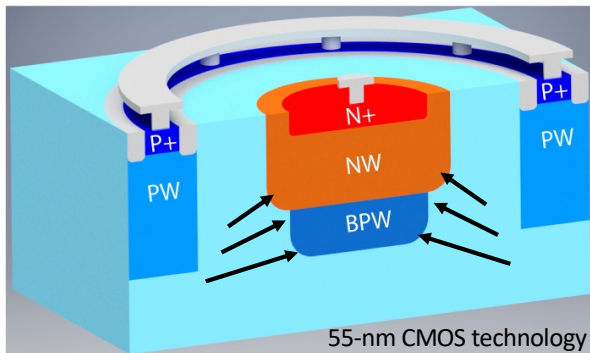
Gramuglia et al. 2021

Comparison of Experimental Results

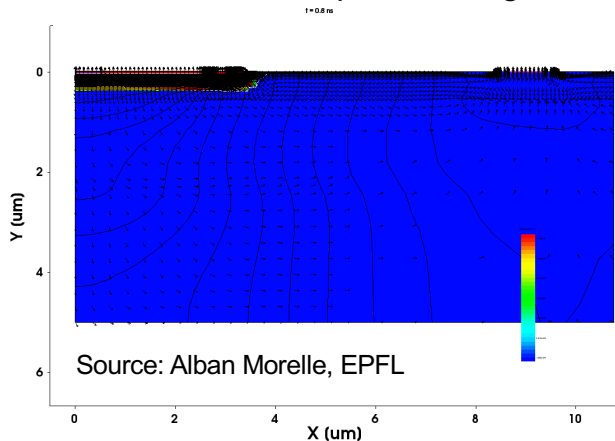
ID	Crystal	Configuration	Light Gain	Energy Resolution (%)	Energy Resolution Improvement
1	BGO	Bare crystal & Opt. Grease	0.55	$20.8 \pm 0.48$	0.74
2	BGO	Bare crystal & Opt. Grease & DBR (top)	0.64	$19.3 \pm 0.26$	0.80
3	BGO	ESR & Opt. Grease	0.98	$15.6 \pm 0.29$	0.99
4	BGO	Teflon & Opt. Grease	1.00	$15.4 \pm 0.19$	1.00
5	BGO	PhC Pattern & Opt. Grease	0.80	$17.2 \pm 0.58$	0.90
6	BGO	PhC Pattern, Teflon & Opt. Grease	1.41	$12.7 \pm 0.36$	1.21
7	BGO	PhC Pattern & Opt. Grease & DBR (top)	0.88	$16.4 \pm 0.57$	0.94
1	LYSO	Bare crystal & Opt. Grease	0.74	$12.2 \pm 0.32$	0.85
2	LYSO	Bare crystal & Opt. Grease & DBR (top)	0.79	$11.8 \pm 0.36$	0.88
3	LYSO	ESR & Opt. Grease	1.00	$10.4 \pm 0.12$	1.00
4	LYSO	Teflon & Opt. Grease	1.00	$10.4 \pm 0.15$	1.00
5	LYSO	PhC Pattern & Opt. Grease	0.85	$11.4 \pm 0.33$	0.91
6	LYSO	PhC Pattern, Teflon & Opt. Grease	1.10	$10.0 \pm 0.24$	1.04
7	LYSO	PhC Pattern & Opt. Grease & DBR (top)	0.86	$11.3 \pm 0.34$	0.92

# Electrical microlenses

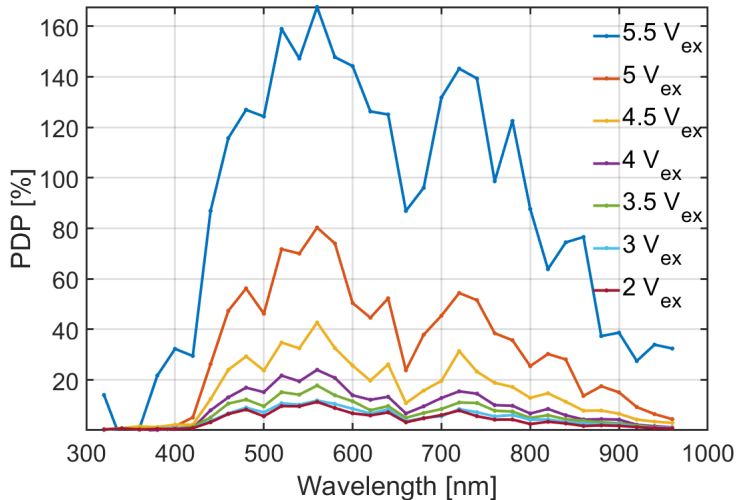
- Innovative use of horizontal E-field
- Multiplication region is reduced, while sensitive region is augmented
- Lateral electric field is used to sweep carriers towards multiplication region



Original idea: Veerappan & Charbon, IISW 2013  
Rediscovered by Canon, who names it 'charge focusing'



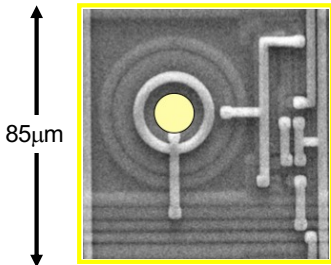
# Electrical microlenses (2)



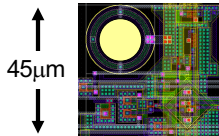
# Large-format cameras

# SPAD scaling

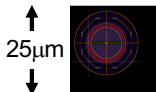
0.8 $\mu$ m CMOS



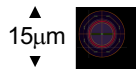
0.35 $\mu$ m CMOS



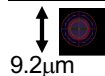
0.13 $\mu$ m CMOS



65nm CMOS



40nm CMOS



3D stacking



Advanced CMOS process should enable:

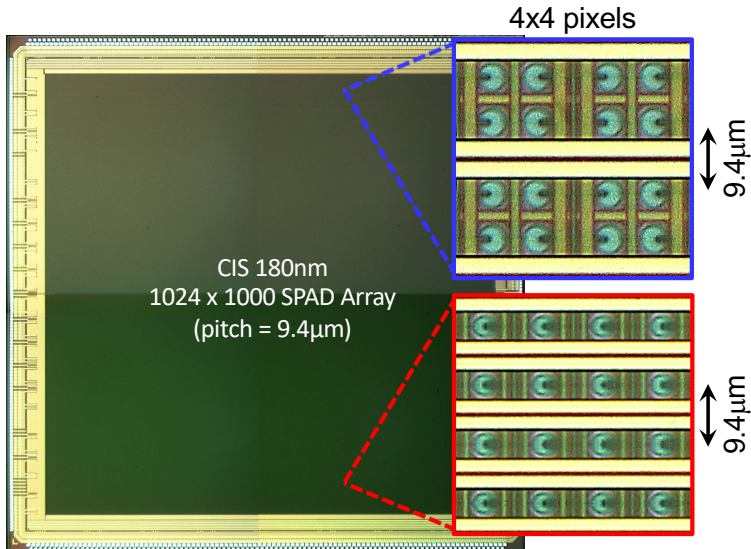
- low pitch
- high performance
- high fill factor



# MegaX: the first SPAD megapixel camera

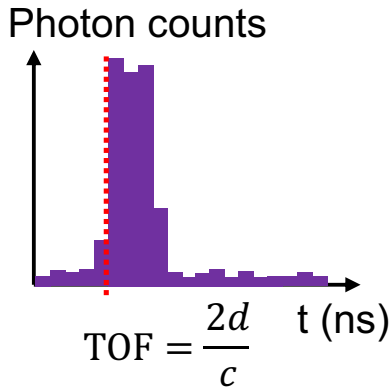
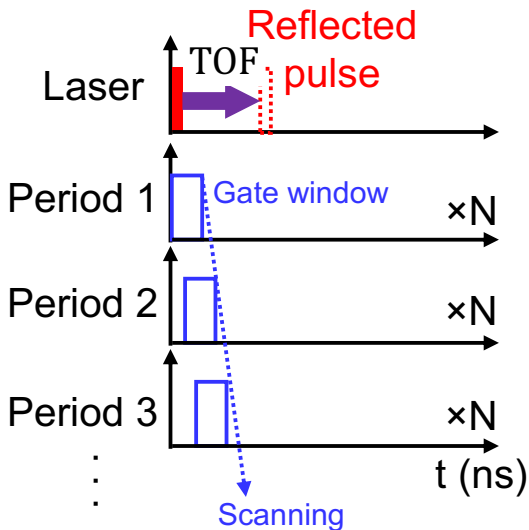
## Features

- 1024 x 1000 pixels
- 9.4 $\mu$ m pitch
- 3.8ns gating
- 24,000 fps
- 24.5Gb/s
- VDD: 1.8V
- VBD: 24.7V



K. Morimoto et al., Optica 2020

# To keep pixels small: time gating

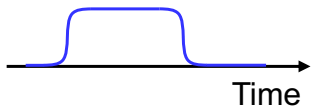


# Multiple reflections

Gating window profile:  $f(t)$

Photon distribution:  $g(t)$

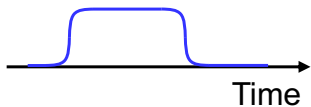
Detected intensity:  $h(t)$



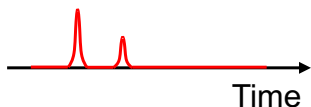
\*



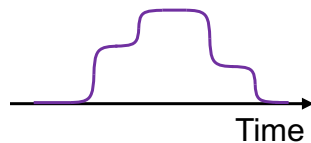
=



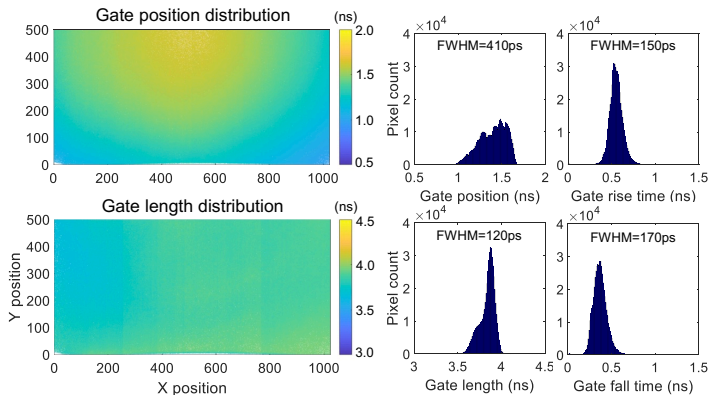
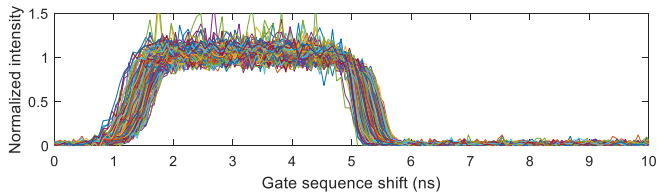
\*



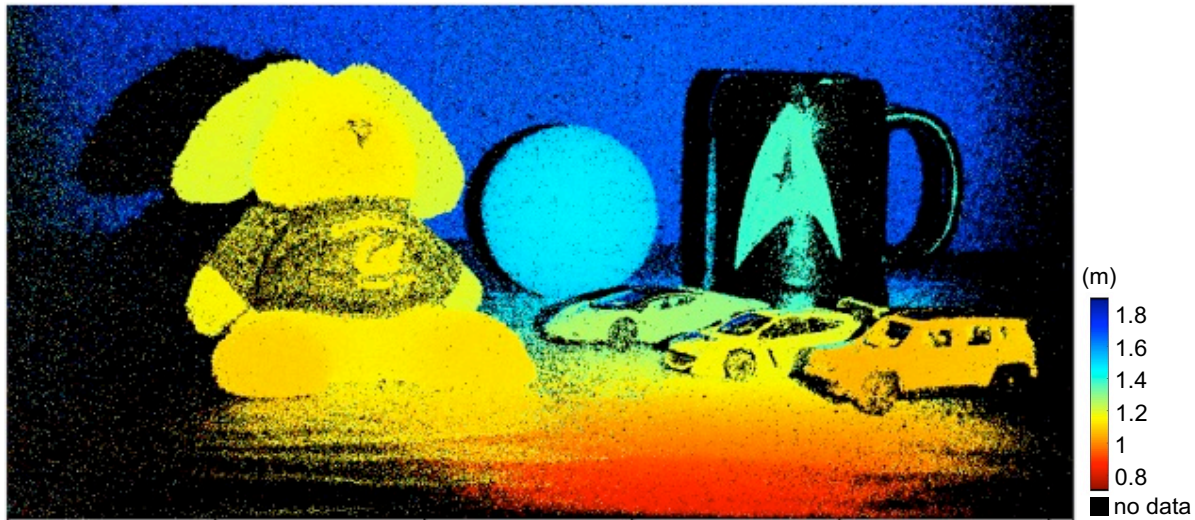
=



# Time gating profile



# MegaX 2D/3D imaging



K. Morimoto et al., Optica 2020

# Light in flight



0.000 ns

K. Morimoto, E. Charbon et al., Phys. Rev. X 2021

# Trends

# Hybrid 3D integration

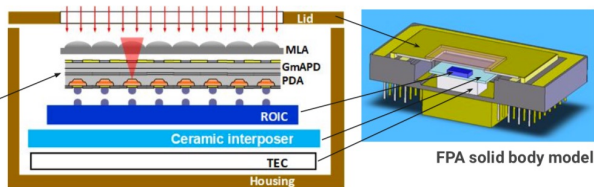
Source: M. Itzler, Argo AI, ISSW 2020

## SPAD Focal Plane Array Integration: 32 x 32

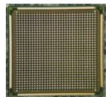


### Focal plane array (FPA) integration:

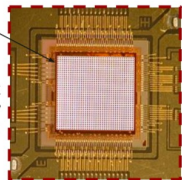
- GaP microlens array (MLA)
- InP GmAPD photodiode array (PDA)
- CMOS readout integrated circuit (ROIC)



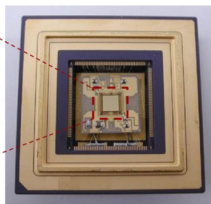
32 x 32 PDA



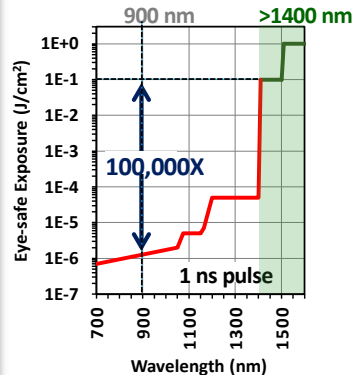
FPA chip stack  
on interposer  
(MLA on top)



100  $\mu\text{m}$  pitch



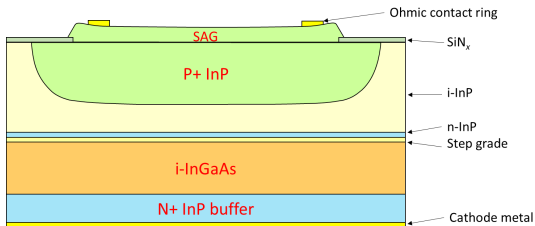
Full FPA  
assembly  
(no lid)



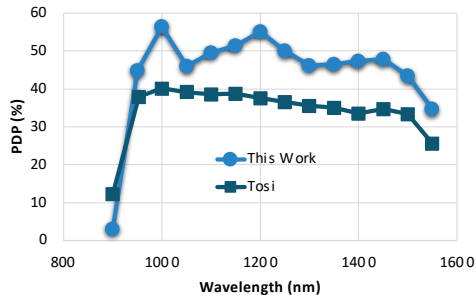
Argo AI Public 10



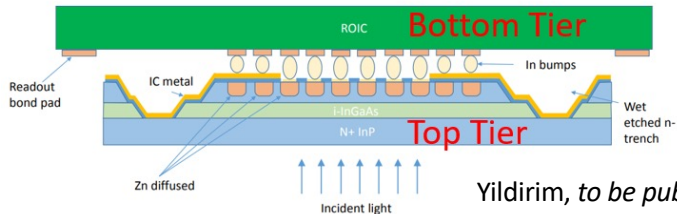
# InGaAs-InP SPADs



SAG = Selective area growth  
Ekin Kizilkan et al., JSTQE, 2022

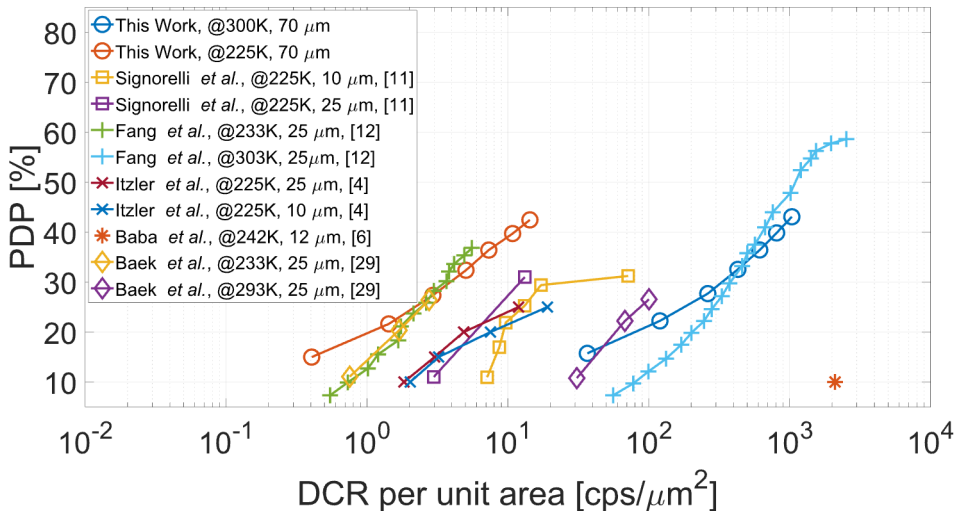


## 96 x 96 InGaAs SPAD pixel array

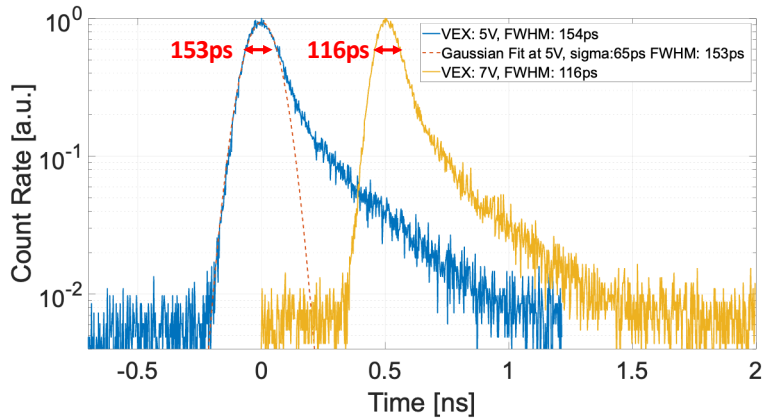


Yildirim, *to be published*, 2024

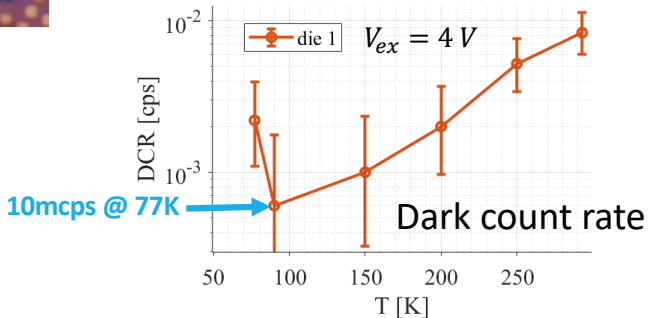
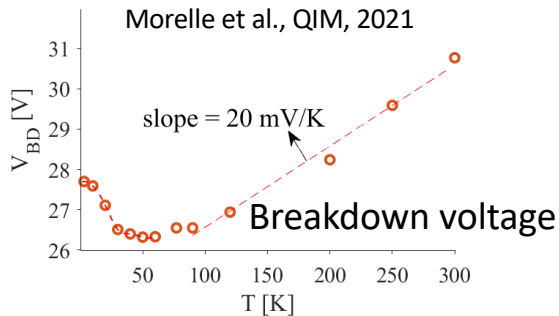
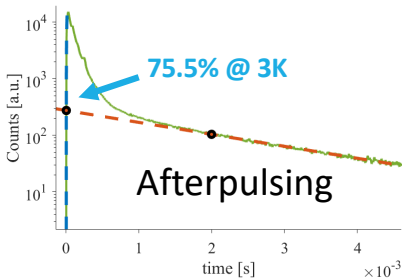
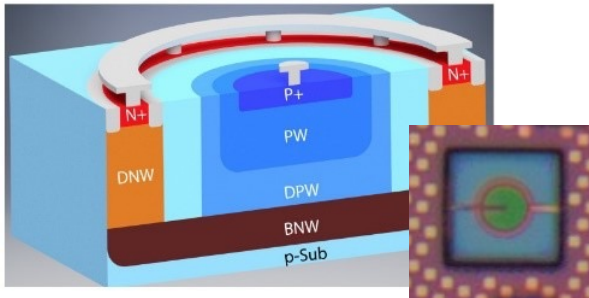
# InGaAs-InP sensitivity vs. noise



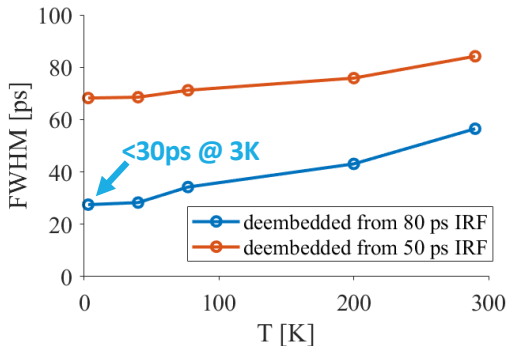
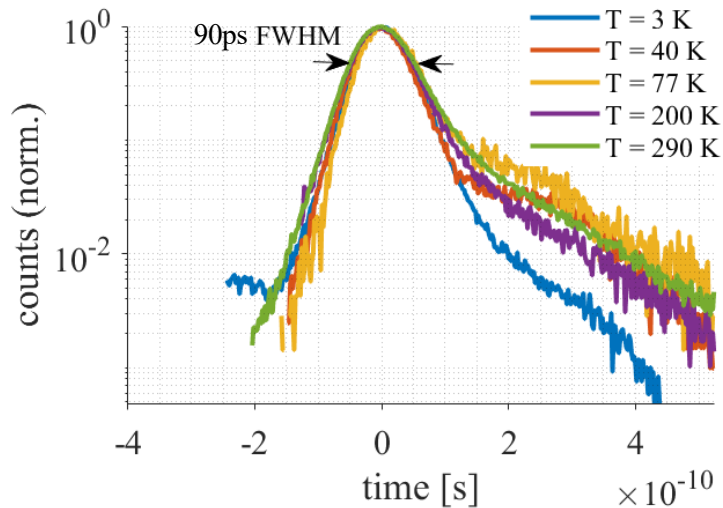
# InGaAs-InP jitter



# Deep-cryogenic 55-nm BSD SPAD/SiPM



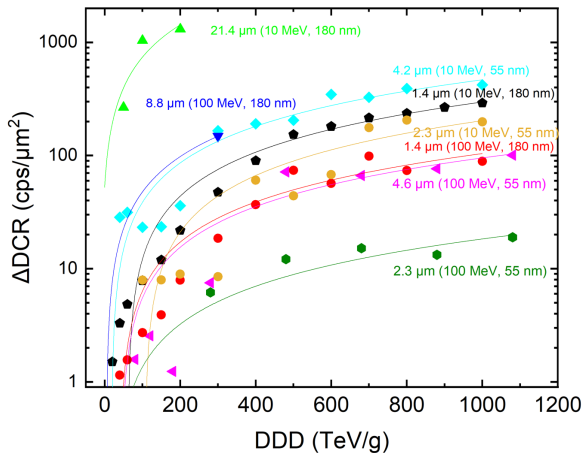
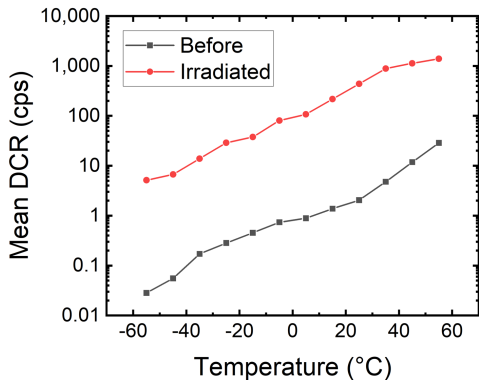
# Deep-cryogenic 55-nm BSD SPAD/SiPM



Morelle et al., QIM, 2022

# Radiation testing of SPADs

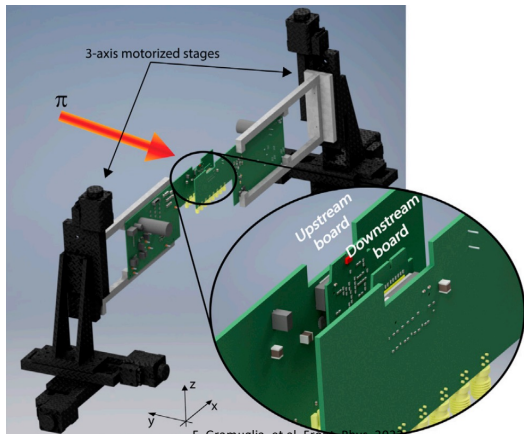
- Proton irradiation with variable fluencies
- 10/100MeV energy
- Different sizes, active areas, temperature



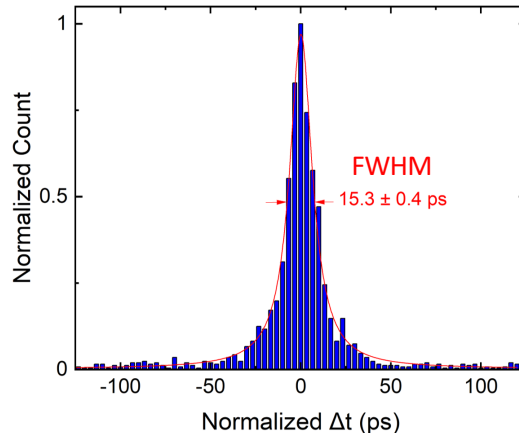
Wu, EPFL Thesis, 2023

Wu et al., EUROCON 2023

# Direct MIP detection



F. Gramuglia, et al. Front. Phys. 2022



Detectors	Resolution <sub>best</sub> (ps)	Time walk	Efficiency
PicoAD	$\sigma = 17.3$	yes	>99%
UFSD	$\sigma = 16^a$	yes	>99%
TIMESPOT	$\sigma = 11.5$	yes	~99%
<b>This work</b>	$\sigma = 6.5$	no	>99%

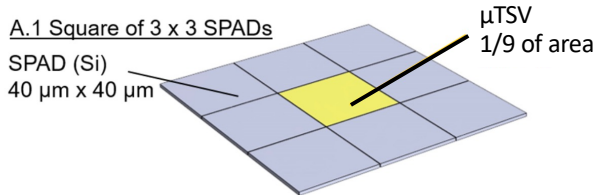
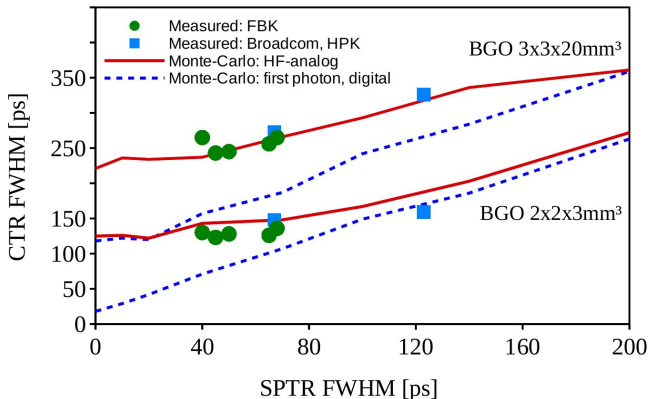
G. Iacobucci et al. 2022

N. Cartiglia et al. 2017

A. Lampis et al. 2023

M.-L. Wu et al. 2023

# The DIGILOG project: high-granularity SiPMs

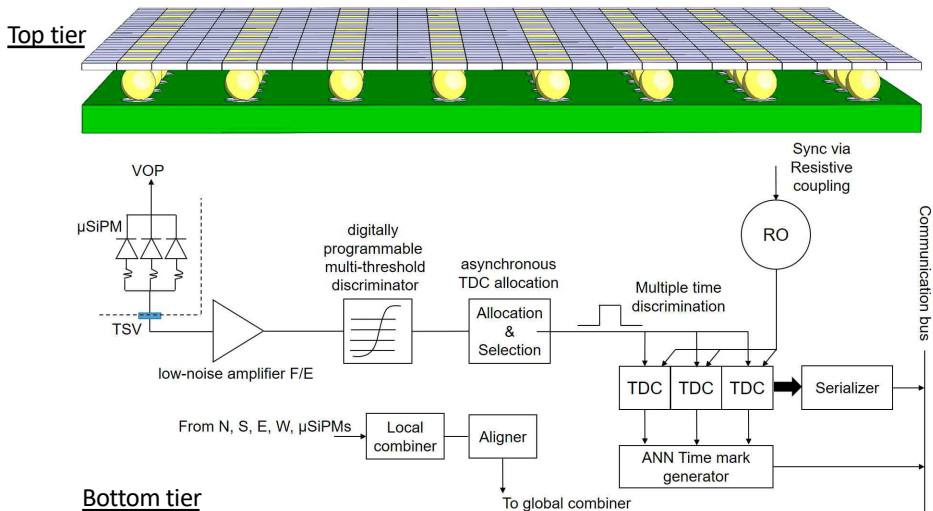


- $\mu$ SiPMs with  $\mu$ TSVs
- $\mu$ ASICs with *in situ* TDCs
- Embedded ANNs
- **Distributed computing**

S. Gundacker, et al., E. Charbon, V. Schultz *NSS* 2023  
S. Gundacker, et al., *to be published* 2023



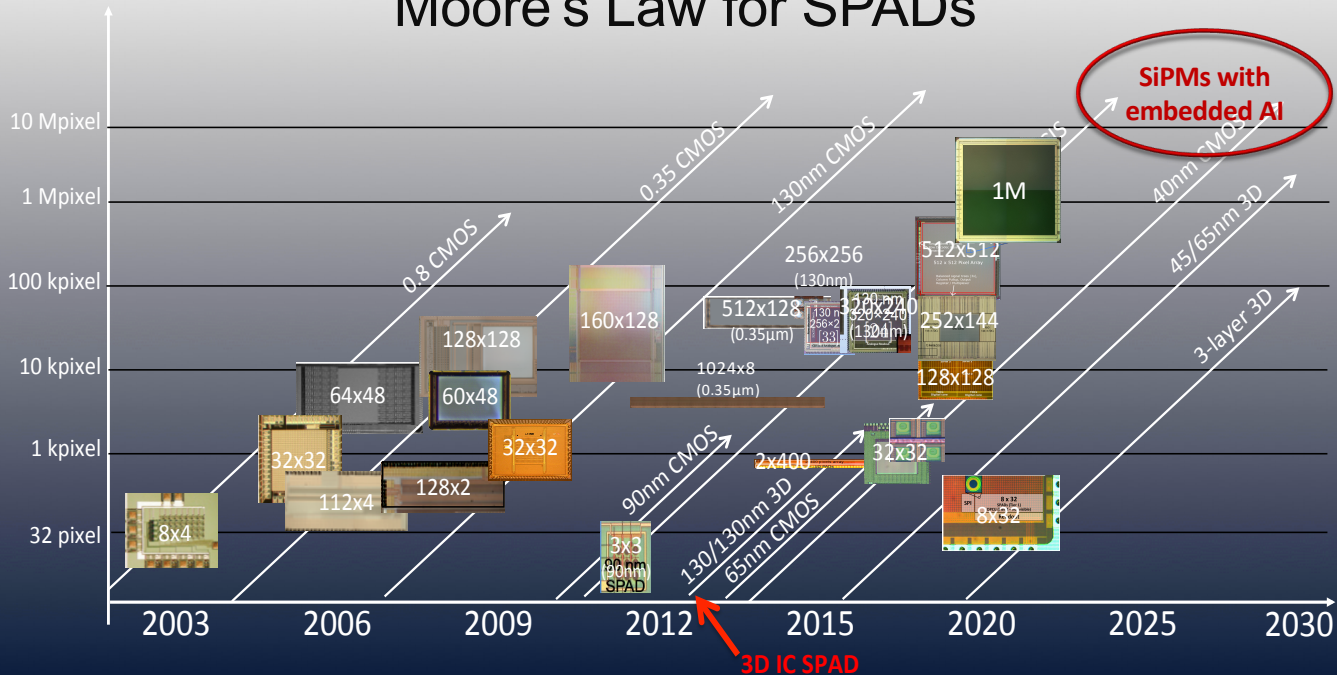
# The DIGILOG project: high-granularity SiPMs (2)



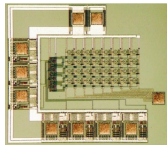
S. Gundacker, et al., E. Charbon, V. Schultz *NSS 2023*  
S. Gundacker, et al., *to be published 2023*

# Conclusions

# Moore's Law for SPADs



# aqualab designs (2004–)



ISSCC 2004



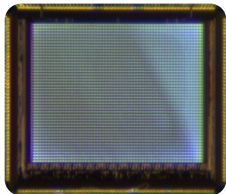
IISW 2011



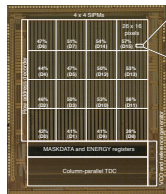
SPIE 2006



ESSCIRC 2007



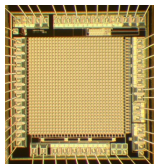
ESSCIRC 2009



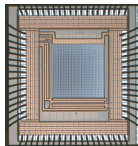
NSS 2012



ISSCC 2007 bis



ISSCC 2005

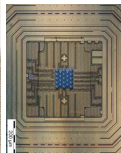


ISSCC 2009

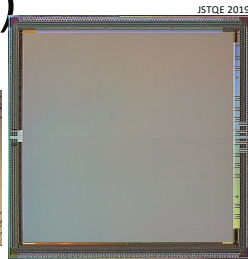
ISSCC 2008



ISSCC 2011



OPEX 2018



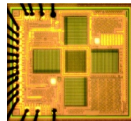
JSTQE 2019



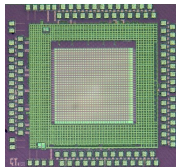
Sensors 2018



ISSCC 2007

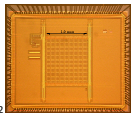


IISW 2013

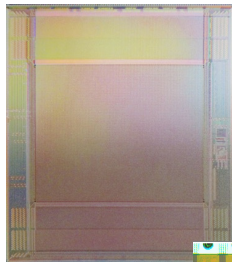


IEDM 2013

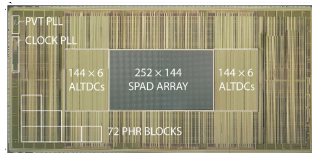
JSSC 2012



ISSCC 2015



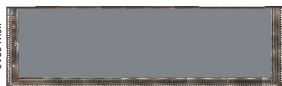
ISSCC 2021



VLSI 2018 / JSSC 2018



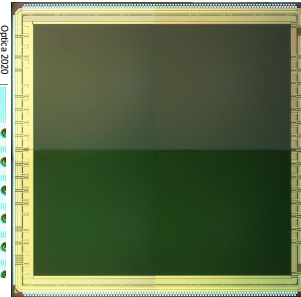
IISW 2013



ISSCC 2015



ISSCC 2018



Optic a 2020

# Quantum imaging

- Quantum LiDAR
- Ghost imaging
- Quantum (ultra-fast) spectroscopy
- Quantum Raman spectroscopy
- Quantum distillation
- Quantum state tomography
- Quantum holography
- Quantum super-resolution
- Quantum plenoptic cameras
- Quanta burst photography

# Take-home messages

- SPAD has emerged as the technology of choice for PET and many other applications, including quantum imaging
- Several technologies, custom and CMOS or CIS have been used to build SiPMs with low noise and high PDE
- 3D-stacking could multiply the impact of these detectors with parallelism and machine learning in the forefront

# Thank You

<http://aqua.epfl.ch>



1<sup>st</sup> User Group Meeting, Les Diablerets, 2022

Next UGM: April 2024